

Features

- AEC-Q101 Qualified
- Split Gate Trench MOSFET Technology
- Excellent Package for Heat Dissipation
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant (Note2) ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

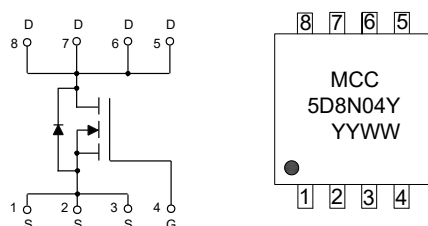
- Operating Junction Temperature Range : -55°C to +175°C
- Storage Temperature Range: -55°C to +175°C
- Thermal Resistance: 60°C/W Junction to Ambient (Note3)
- Thermal Resistance: 2.3°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	70	A
		49	
Pulsed Drain Current (Note4)	I_{DM}	280	A
Total Power Dissipation (Note5)	P_D	65	W
Single Pulsed Avalanche Energy (Note6)	E_{AS}	40	mJ

Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. High Temperature Solder Exemption Applied, see EU Directive Annex 7(a)-I.
3. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.
4. Repetitive rating; pulse width limited by max. junction temperature.
5. P_D is based on max. junction temperature, using junction-case thermal resistance.
6. $T_J = 25^\circ\text{C}$, $V_{DD} = 30\text{V}$, $R_g = 25\Omega$, $V_{GS} = 10\text{V}$, $L = 0.5\text{mH}$.

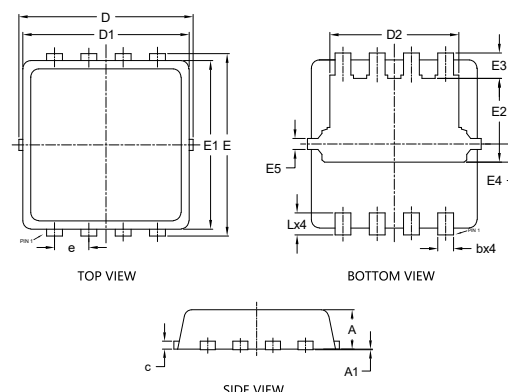
Internal Structure and Marking Code



YYWW: 4 codes in total
YY is the year
WW is the week

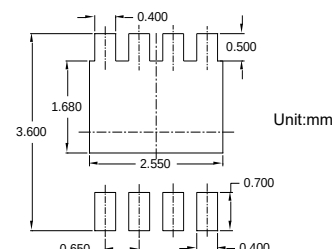
N-CHANNEL MOSFET

PDFN3333



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.028	0.033	0.70	0.85	
A1	0.000	0.002	0.00	0.05	
b	0.008	0.016	0.20	0.40	
c	0.004	0.010	0.10	0.25	
D	0.124	0.136	3.15	3.45	
D1	0.118	0.130	3.00	3.30	
D2	0.089	0.104	2.25	2.65	
E	0.124	0.136	3.15	3.45	
E1	0.114	0.126	2.90	3.20	
E2	0.052	0.068	1.32	1.72	
E3	0.011	0.026	0.28	0.65	
E4	0.013		0.330		TYP
E5	0.008		0.200		TYP
e	0.026		0.650		BSC
L	0.012	0.020	0.300	0.500	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =1mA	40			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =32V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	2.8	4	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A		4.6	5.8	mΩ
Gate Resistance	R _g	f=1MHz,Open Drian		1.5		Ω
Diode Characteristics						
Continuous Body Diode Current	I _S				75	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A			1.2	V
Reverse Recovery Time	t _{rr}	I _F =20A,di/dt=100A/μs		19.5		ns
Reverse Recovery Charge	Q _{rr}			9.7		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =20V,V _{GS} =0V,f=1MHz		627		pF
Output Capacitance	C _{oss}			390		
Reverse Transfer Capacitance	C _{rss}			19		
Total Gate Charge	Q _g	V _{DS} =20V,V _{GS} =10V,I _D =20A		10.6		nC
Gate-Source Charge	Q _{gs}			3.3		
Gate-Drain Charge	Q _{gd}			3.5		
Turn-On Delay Time	t _{d(on)}	V _{DD} =20V, V _{GS} =10V, R _G =3Ω, I _D =20A		8.4		ns
Turn-On Rise Time	t _r			4.2		
Turn-Off Delay Time	t _{d(off)}			12.6		
Turn-Off Fall Time	t _f			4.6		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

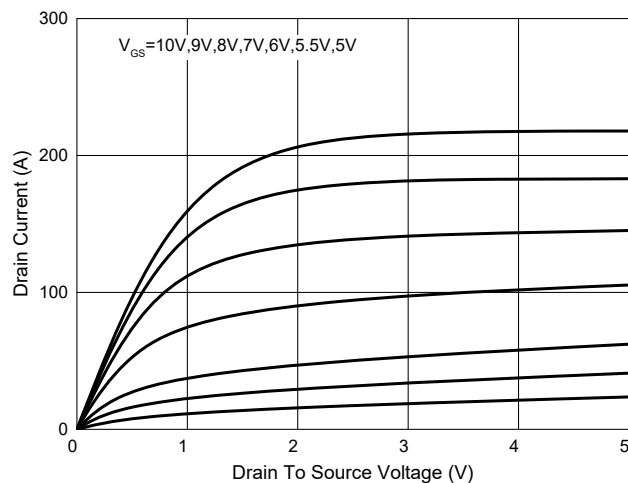


Fig. 2 - Transfer Characteristics

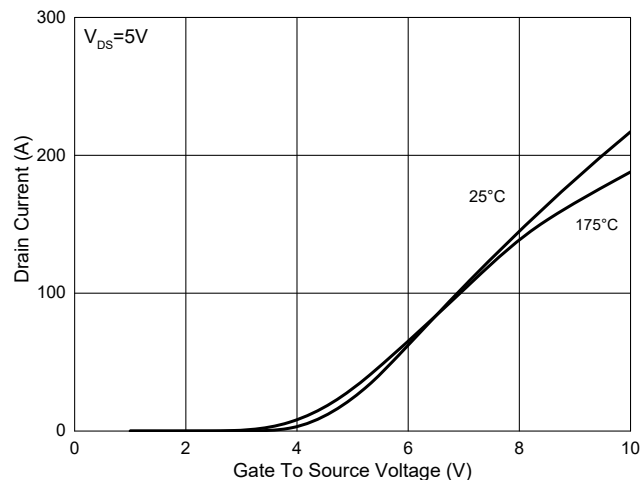


Fig. 3 - $R_{DS(ON)}$ — V_{GS}

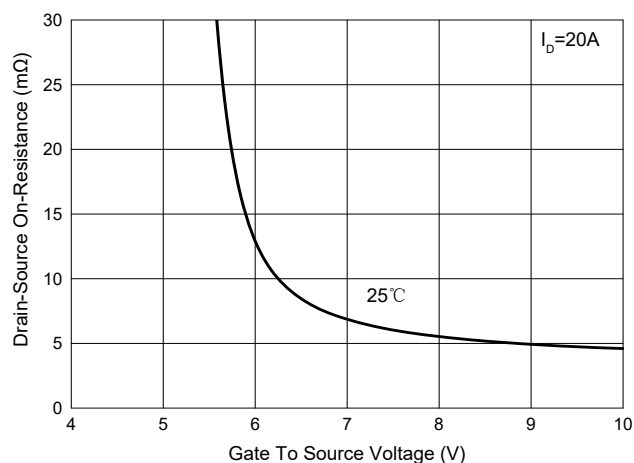


Fig. 4 - $R_{DS(ON)}$ — I_D

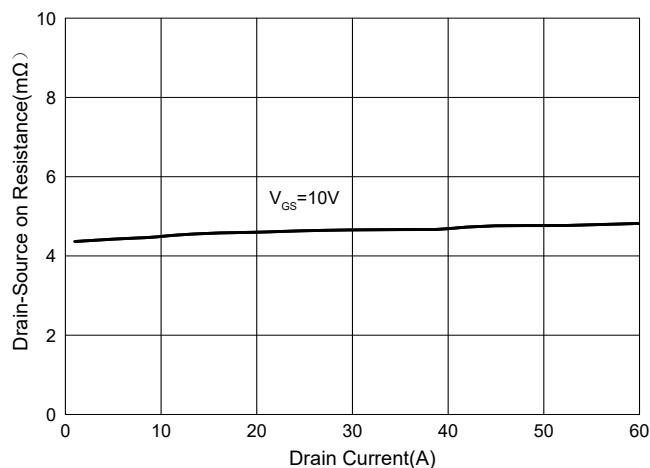


Fig.5 - Capacitance Characteristics

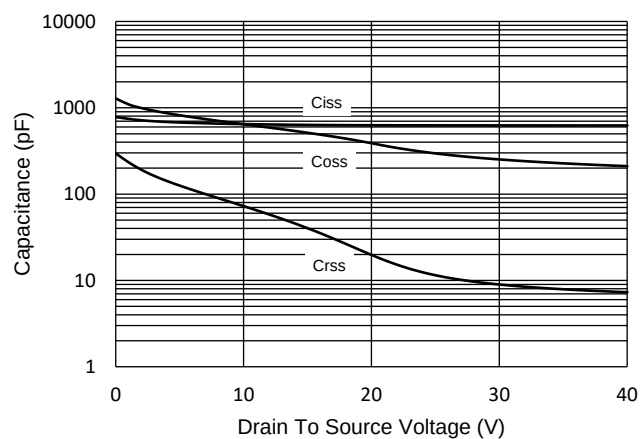
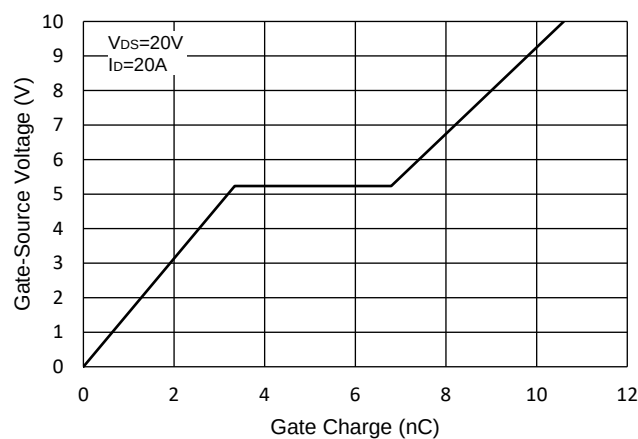


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

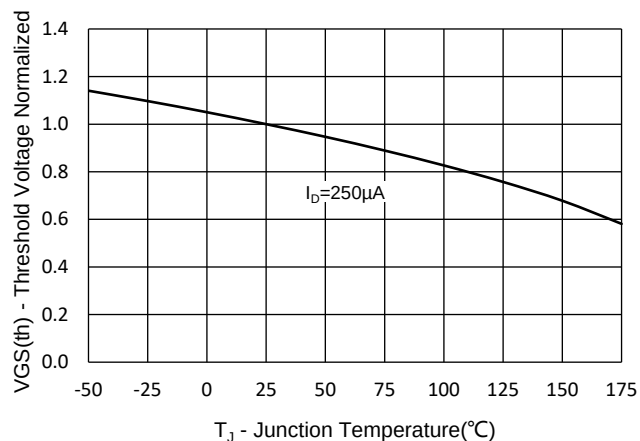


Fig.8-Normalized On Resistance Characteristics

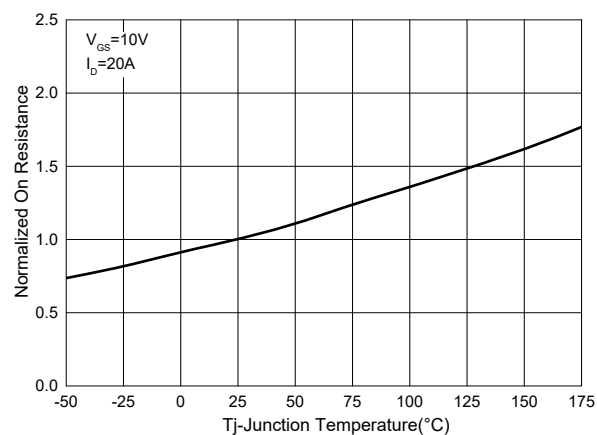


Fig.9 - $I_S - V_{SD}$

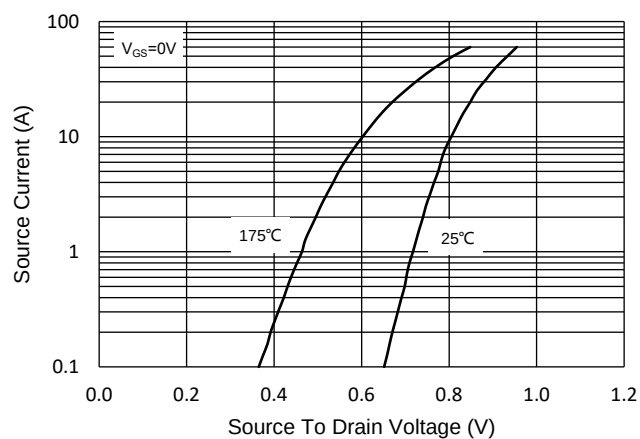


Fig. 10 - Drain Current

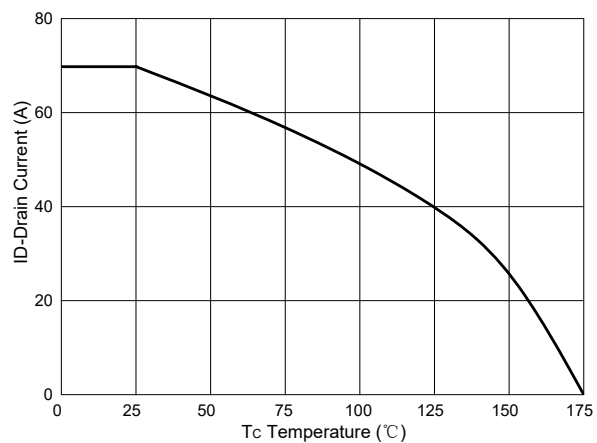
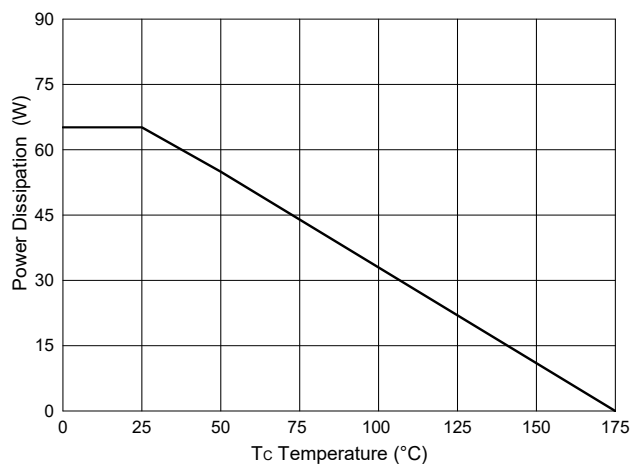


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

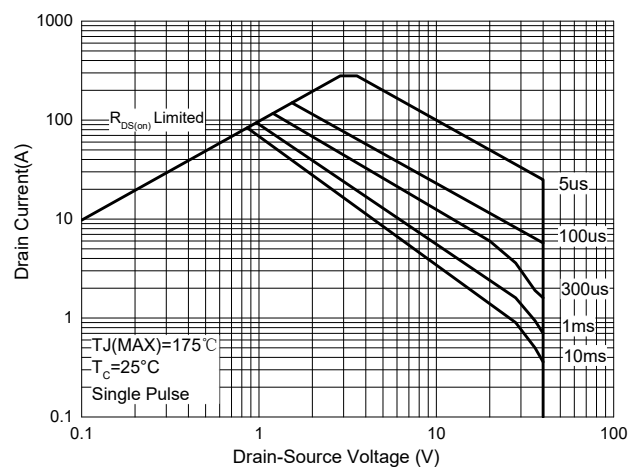
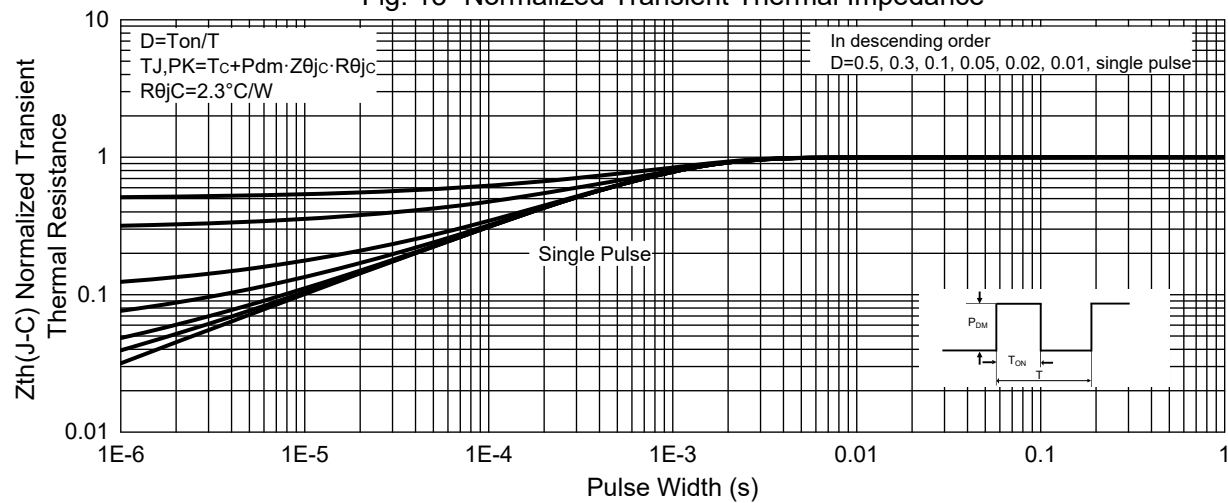


Fig. 13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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